BT137S series BT137M series

GENERAL DESCRIPTION

Passivated triacs in a plastic suitable for envelope, surface mounting, intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal performance. cycling Typical applications include motor control, industrial and domestic lighting, heating and static switching.

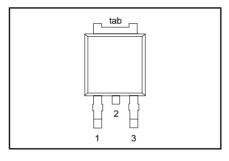
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
	BT137S (or BT137M)- BT137S (or BT137M)- BT137S (or BT137M)-	500 500F 500G	600 600F 600G	800 800F 800G	
V_{DRM}	Repetitive peak off-state	500	600	800	V
I _{T(RMS)}	voltages RMS on-state current Non-repetitive peak on-state current	8 65	8 65	8 65	A A

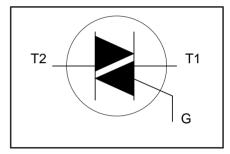
PINNING - SOT428

PIN NUMBER	Standard S	Alternative M
1	MT1	gate
2	MT2	MT2
3	gate	MT1
tab	MT2	MT2

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V_{DRM}	Repetitive peak off-state voltages		-	-500 500 ¹	-600 600 ¹	-800 800	V
I_{TSM}	RMS on-state current Non-repetitive peak on-state current	full sine wave; $T_{mb} \le 102 ^{\circ}\text{C}$ full sine wave; $T_{j} = 25 ^{\circ}\text{C}$ prior to surge	-		8		A
		t = 20 ms t = 16.7 ms	-		65 71		A A
l ² t dl _T /dt	I ² t for fusing Repetitive rate of rise of on-state current after	t = 10.7 ms t = 10 ms $I_{TM} = 12 \text{ A}; I_{G} = 0.2 \text{ A};$ $dI_{G}/dt = 0.2 \text{ A}/\mu\text{s}$	-		21		A ² s
	triggering	T2+ G+ T2+ G- T2- G- T2- G+	-		50 50 50 10		A/μs A/μs A/μs A/μs
I _{GM} V _{GM} P _{GM}	Peak gate current Peak gate voltage Peak gate power	12- 0+	-		2 5 5		Α A V W
P _{G(AV)} T _{stg} T _j	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- -40 -		0.5 150 125		O, O,

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 $A/\mu s$.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	full cycle half cycle pcb (FR4) mounted; footprint as in Fig.14	1 1 1	- - 75	2.0 2.4 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.		MAX.		UNIT
		BT137S- (or BT137M)				F	G	
I _{GT}	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ T2+ G+	_	5	35	25	50	mA
		T2+ G-	-	8	35	25	50	mA
		T2- G- T2- G+	-	11 30	35 70	25 70	50	mA m^
I _L	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	_	30	70	10	100	mA
	3	T2+ G+	-	7	30	30	45	mA
		T2+ G- T2- G-	-	16 5	45 30	45 30	60 45	mA mA
		T2- G+	-	7	45	45	60	mA
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	5	20	20	40	mA
V _T	On-state voltage	$I_{T} = 10 \text{ A}$	-	1.3		1.65		V
V_{GT}	Gate trigger voltage	$\dot{V}_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ $\dot{V}_D = 400 \text{ V}; I_T = 0.1 \text{ A};$	0.25	0.7 0.4		1.5		V
		T _i = 125 °C	0.23	0.4		_		
I _D	Off-state leakage current	$V_D = V_{DRM(max)};$ $T_i = 125 °C$	-	0.1		0.5		mA

DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	BT137S-(or BT137M) $V_{DM} = 67\% V_{DRM(max)};$ $T_j = 125 ^{\circ}C;$ exponential	 100	F 50	G 200	250	-	V/μs
dV _{com} /dt	Critical rate of change of commutating voltage	waveform; gate open circuit $V_{DM} = 400 \text{ V}; T_j = 95 ^{\circ}\text{C};$ $I_{T(RMS)} = 8 \text{ A};$ $dI_{com}/dt = 3.6 \text{ A/ms};$ gate	-	-	10	20	-	V/μs
\mathbf{t}_{gt}	Gate controlled turn-on time	open circuit $I_{TM} = 12 \text{ A}$; $V_D = V_{DRM(max)}$; $I_G = 0.1 \text{ A}$; $dI_G/dt = 5 \text{ A}/\mu \text{s}$	-	-	-	2	-	μs

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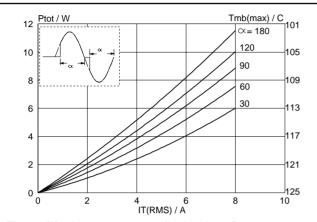


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

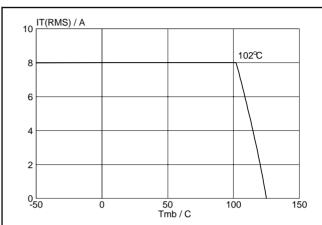


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

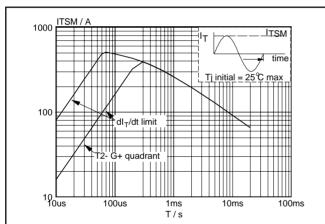


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

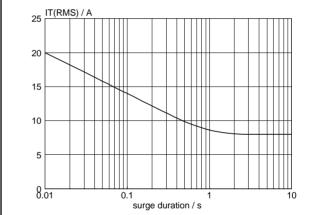


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \le 102$ °C.

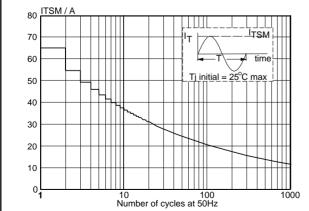


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

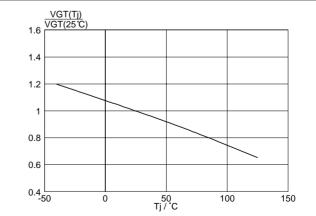
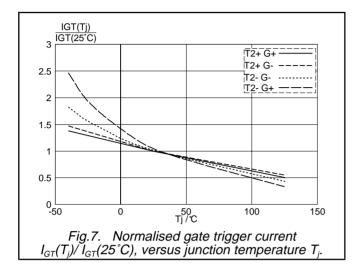
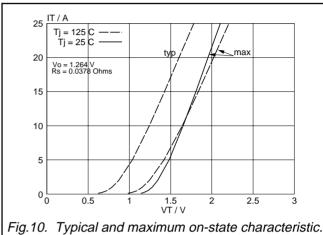
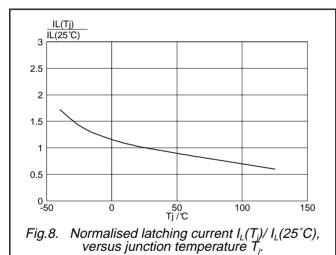


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_j .

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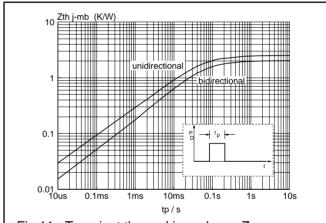


Fig.11. Transient thermal impedance $Z_{th i-mb}$, versus pulse width t_n.

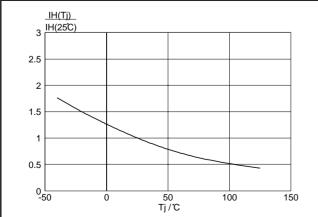


Fig.9. Normalised holding current $I_H(T_i)/I_H(25^{\circ}C)$, versus junction temperature T_i .

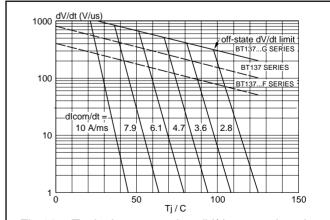
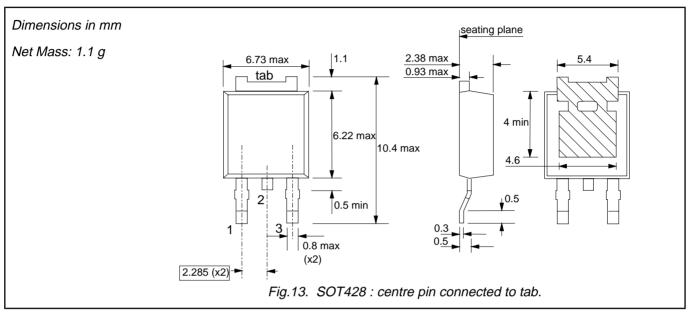


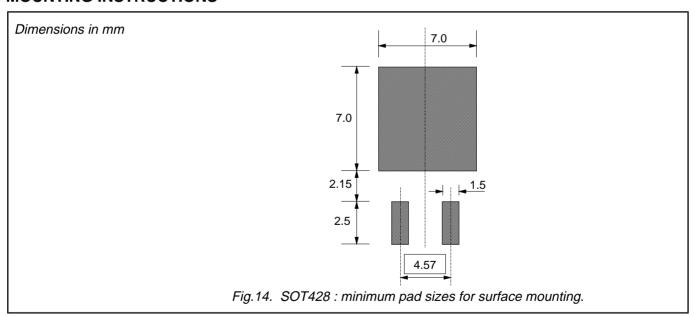
Fig.12. Typical commutation dV/dt versus junction temperature, parameter commutation dl₁/dt. The triac should commutate when the dV/dt is below the value on the appropriate curve for pre-commutation dI_{τ}/dt .

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MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

1. Plastic meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

Triacs

BT137S series BT137M series

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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